

# Field Effect Transistor

## Silicon N Channel MOS Type ( $\pi$ -MOS II.5)

## High Speed, High Current DC-DC Converter,

## **Relay Drive and Motor Drive Applications**

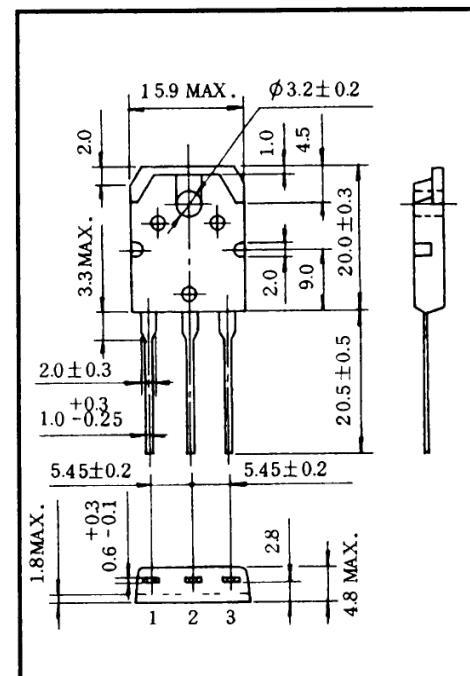
## Features

- Low Drain-Source ON Resistance
    - $R_{DS(ON)} = 1.1\Omega$  (Typ.)
  - High Forward Transfer Admittance
    - $|Y_{fs}| = 4.0S$  (Typ.)
  - Low Leakage Current
    - $I_{DSS} = 300\mu A$  (Max.) @  $V_{DS} = 720V$
  - Enhancement-Mode
    - $V_{th} = 1.5 \sim 3.5V$  @  $V_{DS} = 10V$ ,  $I_D = 1mA$

### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ )

CHARACTERISTIC	SYMBOL	RATING	UNIT
Drain-Source Voltage	$V_{DSS}$	900	V
Drain-Gate Voltage ( $R_{GS} = 20\text{k}\Omega$ )	$V_{DGR}$	900	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Drain Current	DC	$I_D$	9
	Pulse	$I_{DP}$	27
Drain Power Dissipation ( $T_c = 25^\circ\text{C}$ )	$P_D$	150	W
Channel Temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 ~ 150	$^\circ\text{C}$

## **Industrial Applications**



1. GATE
  2. DRAIN (HEAT SINK)
  3. SOURCE

JEDEC

EIAJ SC-65

TOSHIBA 2-16C1B

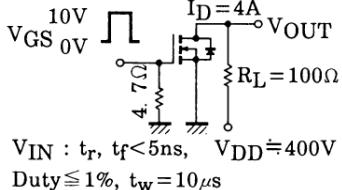
Weight : 4.6g

### **Thermal Characteristics**

<b>CHARACTERISTIC</b>	<b>SYMBOL</b>	<b>MAX.</b>	<b>UNIT</b>
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	0.833	°C/W
Thermal Resistance, Channel to Ambient	$R_{th(ch-a)}$	50	°C/W

This transistor is an electrostatic sensitive device. Please handle with care.

## Electrical Characteristics (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±25V, V <sub>DS</sub> = 0V	—	—	±100	nA	
Drain Cut-off Current	I <sub>DSS</sub>	V <sub>DS</sub> = 720V, V <sub>GS</sub> = 0V	—	—	300	μA	
Drain-Source Breakdown Voltage	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10mA, V <sub>GS</sub> = 0V	900	—	—	V	
Gate Threshold Voltage	V <sub>th</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	1.5	—	3.5	V	
Drain-Source ON Resistance	R <sub>DS (ON)</sub>	I <sub>D</sub> = 4A, V <sub>GS</sub> = 10V	—	1.1	1.4	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 20V, I <sub>D</sub> = 4A	2.0	4.0	—	S	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz	—	1300	1800	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>		—	100	150		
Output Capacitance	C <sub>oss</sub>		—	180	260		
Switching Time	Rise Time	t <sub>r</sub>		—	25	50	ns
	Turn-on Time	t <sub>on</sub>		—	40	80	
	Fall Time	t <sub>f</sub>		—	20	40	
	Turn-off Time	t <sub>off</sub>		—	100	200	
Total Gate Charge (Gate-Source Plus Gate-Drain)	Q <sub>g</sub>	V <sub>DD</sub> = 400V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 9A	—	120	240	nC	
Gate-Source Charge	Q <sub>gs</sub>		—	70	—		
Gate-Drain ("Miller") Charge	Q <sub>gd</sub>		—	50	—		

## Source-Drain Diode Ratings and Characteristics (Ta = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I <sub>DR</sub>	—	—	—	9	A
Pulse Drain Reverse Current	I <sub>DRP</sub>	—	—	—	27	A
Diode Forward Voltage	V <sub>DSF</sub>	I <sub>DR</sub> = 9A, V <sub>GS</sub> = 0V	—	—	-2.0	V